

Abstract of the Disclosure

An integral polishing pad includes an elastic support layer and a polishing layer, which is formed on the elastic support layer and has a higher hardness than the elastic support layer. The elastic support layer and the polishing layer are made from materials chemically compatible with each other so that a structural border between the elastic support layer and the polishing layer does not exist. In addition, the integral polishing pad also includes a transparent region, which is transparent to a light source used to detect the surface state of an object being polished and integrated with the other elements of the integral polishing pad. The integral polishing pad has high planarization efficiency and uniform properties, and thus can be reliably used for polishing. In addition, the integral polishing pad prevents a congestion of a polishing slurry and facilitates delivery of the polishing slurry. The integral polishing pad does not need an adhesive for connecting elements or a process for bonding the elements, thereby simplifying manufacturing processes.